

PALM INTRANET

Day : Monday
 Date: 10/18/2004
 Time: 11:13:09

Inventor Name Search Result

Your Search was:

Last Name = LANE

First Name = RYAN

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>60569187</u>	Not Issued	020	05/07/2004	VIDEO GAME PLATFORM AND USER INTERFACE	9 LANE, RYAN THOMAS
<u>60547756</u>	Not Issued	020	02/24/2004	OPTIMIZED POWER DELIVERY TO HIGH SPEED, HIGH PIN COUNT DEVICES	LANE, RYAN
<u>60465303</u>	Not Issued	159	04/24/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	LANE, RYAN
<u>60443817</u>	Not Issued	159	01/30/2003	AREA ARRAY PACKAGE WITH IMPROVED RELIABILITY OF SOLDER JOINTS	LANE, RYAN
<u>60399091</u>	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	LANE, RYAN
<u>10830188</u>	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	LANE, RYAN
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	LANE, RYAN
<u>10443524</u>	Not Issued	161	05/21/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	LANE, RYAN

<u>10393666</u>	<u>6762495</u>	150	03/20/2003	AREA ARRAY PACKAGE WITH NON-ELECTRICALLY CONNECTED SOLDER BALLS	LANE, RYAN
-----------------	----------------	-----	------------	---	------------

Inventor Search Completed: No Records to Display.

Search Another:	Last Name	First Name
	<input type="text" value="LANE"/>	<input type="text" value="RYAN"/>
Inventor	<input type="button" value="Search"/>	

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | Home page

PALM INTRANET

Day : Monday
 Date: 10/18/2004
 Time: 11:13:35

Inventor Name Search Result

Your Search was:

Last Name = REYES

First Name = EDWARD

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>60465303</u>	Not Issued	159	04/24/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	REYES, EDWARD
<u>60443817</u>	Not Issued	159	01/30/2003	AREA ARRAY PACKAGE WITH IMPROVED RELIABILITY OF SOLDER JOINTS	REYES, EDWARD
<u>60399091</u>	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	REYES, EDWARD
<u>10830188</u>	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	REYES, EDWARD
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	REYES, EDWARD
<u>10443524</u>	Not Issued	161	05/21/2003	TECHNIQUE FOR STACKING VARIABLE SIZE DICE IN A PACKAGE WITH WIRE BOND AND FLIP CHIP TECHNOLOGY	REYES, EDWARD
<u>10393666</u>	<u>6762495</u>	150	03/20/2003	AREA ARRAY PACKAGE WITH NON-ELECTRICALLY CONNECTED SOLDER BALLS	REYES, EDWARD
<u>10282795</u>	6787901	150	10/28/2002	METHOD AND APPARATUS	REYES,

				FOR DIE STACKING	EDWARD
09932160	6680219	150	08/17/2001	METHOD AND APPARATUS FOR DIE STACKING	REYES, EDWARD
<u>08282205</u>	<u>5407082</u>	150	07/28/1994	AUTOMATIC EJECTOR RATE NORMALIZER USING MULTIPLE TRIP LEVELS ESTABLISHED IN A MASTER CHANNEL	REYES , EDWARD G.

Inventor Search Completed: No Records to Display.

Search Another:
Inventor

Last Name

First Name

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | Home page

PALM INTRANET

Day : Monday
 Date: 10/18/2004
 Time: 11:14:28

Inventor Name Search Result

Your Search was:

Last Name = VEATCH

First Name = MARK

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>60547756</u>	Not Issued	020	02/24/2004	OPTIMIZED POWER DELIVERY TO HIGH SPEED, HIGH PIN COUNT DEVICES	VEATCH, MARK
<u>60399091</u>	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	VEATCH, MARK
<u>10830188</u>	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	VEATCH, MARK
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR A ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	VEATCH, MARK
<u>07162166</u>	<u>4866660</u>	150	02/29/1988	OPTOELECTRONIC DEVICES BASED ON INTERFERENCE INDUCED CARRIER MODULATION	VEATCH , MARK S

Inventor Search Completed: No Records to Display.

Search Another:**Inventor****Last Name****First Name**

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | Home page

 PALM INTRANET

Day : Monday
 Date: 10/18/2004
 Time: 11:14:36

Inventor Name Search Result

Your Search was:

Last Name = GREGORICH

First Name = TOM

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>60525540</u>	Not Issued	020	11/25/2003	USE (SMP) STACKED MODULE PACKAGE TO DECOUPLE AND STANDARDIZE THE INTERFACE BETWEEN MULTIPLE DIE IN ONE PACKAGE	GREGORICH, TOM
<u>60524331</u>	Not Issued	020	11/21/2003	USE (MIP) MODULE-IN-PACKAGE SOLUTION TO DECOUPLE AND STANDARDIZE DIGITAL AND MEMORY INTERFACE	GREGORICH, TOM
<u>60443817</u>	Not Issued	159	01/30/2003	AREA ARRAY PACKAGE WITH IMPROVED RELIABILITY OF SOLDER JOINTS	GREGORICH, TOM
<u>60399091</u>	Not Issued	159	07/26/2002	LAMINATE SUBSTRATE DESIGN FEATURES TO ACCOMMODATE SMALLER MINIMUM IN AREA ARRAY PACKAGES WITH WIREBOND TECHNOLOGY	GREGORICH, TOM
<u>10830188</u>	Not Issued	030	04/21/2004	METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	GREGORICH, TOM
<u>10624787</u>	Not Issued	071	07/21/2003	METHOD FOR A ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES	GREGORICH, TOM
<u>10393666</u>	6762495	150	03/20/2003	AREA ARRAY PACKAGE WITH NON-ELECTRICALLY CONNECTED SOLDER	GREGORICH, TOM

BALLS**Inventor Search Completed: No Records to Display.**

Last Name	First Name
GREGORICH	TOM

Search Another:
Inventor

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | Home page

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	195	array and die same attach\$ and bond\$ with wire and bond same finger	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 16:59
2	BRS	172	array and die same attach\$ and bond\$ with wire and bond same (staggered or offset or offset)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:02
3	BRS	2	substrate and die and bond adj pad and bond adj island and wire adj bond and (enapsulating encapsulate encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:15
4	BRS	599	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:15
5	BRS	25	substrate and die and bond adj pad and wire adj bond and (enapsulating encapsulate encapsulated) and BGA and LGA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:15
6	BRS	4	("5545923" "6407456").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:19
7	BRS	325	438/617.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/15 17:45